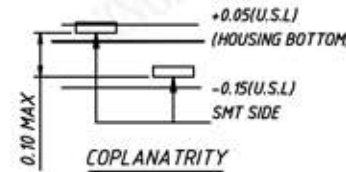
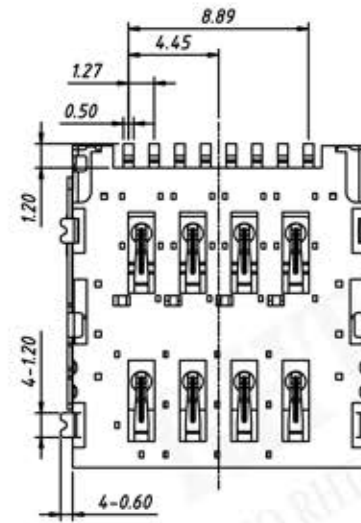
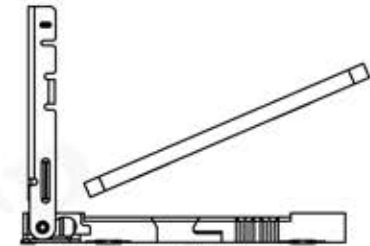


SECTION:A-A



COPLANARITY



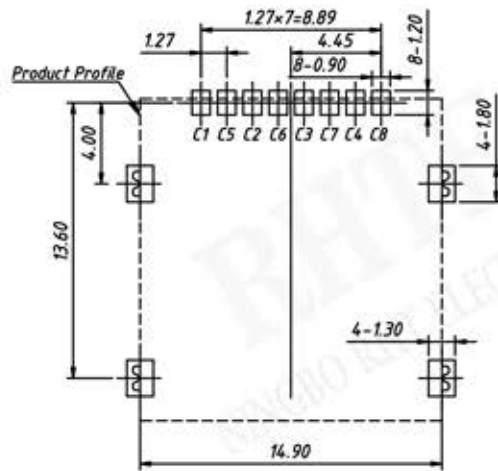
STEP 1 INSERT Micro-SIM CARD



STEP 2 PUSH THE SHELL



STEP 3 FINISH



RECOMMENDED PCB LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

SIM Card	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

Material

Housing:Thermoplastic,UL 94 V-0.

Terminal:Phosphor Bronze,T=0.15,Ni

Plated Under,Au Plated On Contact Area,G/F Plated On Solder-tail.

Shell:Stainless Steel,T=0.15,Ni Plated Under,G/F Plated On Solder-tail.

Electrical

Contact Resistance:60mΩ Max.

Insulation Resistance:1000MΩ Min.

Dielectric Withstanding Voltage:500V AC For 1 Minute.

Operation Temperature Range:-25°C TO +70°C.

Durability:5000 Cycles.